

and develop the resist pattern to leave the resist film on the portion where no wiring is formed.

Step 4: On the portion of the multilayer copper clad laminate where no wiring is formed, electrolytic copper plating is performed to form outer layer wiring pattern and then plating resist is removed followed by etching of the copper layer on the multilayer copper clad laminate to finish multilayer wiring board.

ABSTRACT

The present invention discloses a technology for a printed wiring board which uses a copper foil without roughening treatment. Therefore, electrodeposited copper foil with carrier foil which is sequentially constituted with carrier foil, bonding interface layer, electrodeposited copper foil with smooth surface on both side and a resin layer is employed. The resin composition constituting the resin layer is composed of 20 to 80 parts by weight of an epoxy resin which includes curing agent, 20 to 80 parts by weight of a solvent soluble aromatic polyamide resin polymer and curing accelerator in a suitable amount if required.